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What Are <u>Embedded - Microcontrollers - Application Specific</u>?

Application enacific microcontrollars are anaineared to

Details	
Product Status	Obsolete
Applications	Power Line Communications
Core Processor	ADD8051C3A
Program Memory Type	SRAM
Controller Series	-
RAM Size	32K x 8
Interface	SPI, UART
Number of I/O	14
Voltage - Supply	3V ~ 3.6V
Operating Temperature	-40°C ~ 85°C
Mounting Type	Surface Mount
Package / Case	120-LQFP
Supplier Device Package	120-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atpl210a-a1u-y

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

## **Atmel ATPL210A**



## **PRIME compliant Power Line Communications SoC**

#### **SUMMARY DATASHEET**

#### **Features**

- Core
  - ADD8051C3A enhanced 8051 core
  - Speedups up to x5 vs. standard 8051 microcontroller
- Modem
  - Power Line Carrier Modem for 50 and 60 Hz mains
  - 97-carrier OFDM PRIME compliant
  - Baud rate Selectable: 21400 to 128600 bps
  - Differential BPSK, QPSK, 8-PSK modulations
- Memories
  - 32Kbytes on-chip SRAM
  - Up to 256Kbytes external SRAM
- In-circuit serial flash programming
- Auto boot-loading program from serial flash
- Automatic Gain Control and signal amplitude tracking
- Embedded on-chip DMAs
- Automatic code encryption during boot loading
- Media Access Control
  - Viterbi decoding and CRC PRIME compliant
  - 128-bit AES encryption
  - Channel sensing and collision pre-detection
- Peripherals
  - Two 2-wire UARTs
  - Two SPI. SPI to serial flash and External RTC. Buffered SPI to external metering IC
  - Programmable Watchdog
  - Up to 14 I/O lines
- Package
  - 120-lead LQFP, 14 x 14 mm, pitch 0.4 mm
  - · Pb-free and RoHS compliant
- Typical Applications
  - Automated Meter Reading (AMR) & Advanced Meter Management (AMM)
  - Street lighting
  - Home Automation

## **Description**

The ATPL210 is a Power Line Communications System on Chip, which implements a full PRIME compliant PLC modem. It includes an enhanced 8051 microcontroller (IP core ADD8051C3A), a Medium Access Controller (MAC) (IP core ADD1221) and a Modem circuit (IP core ADD1321) for power line medium using OFDM modulation compatible with PRIME specifications.

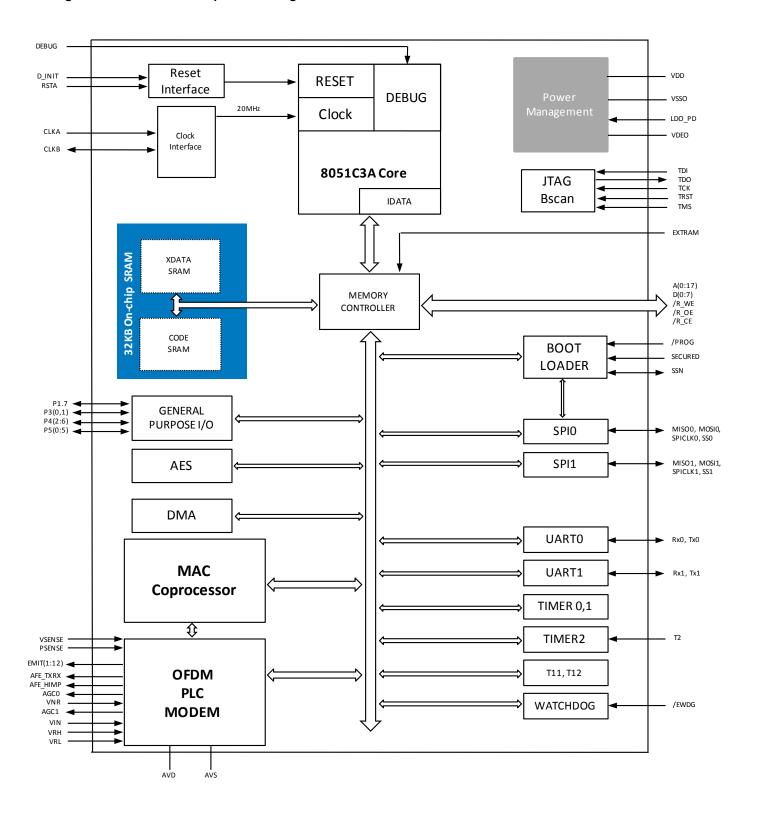
ATPL210 is oriented to high performance & robust AMR systems. The ATPL210 is designed to be used by meter manufacturers to provide a low cost and compact solution for AMR & AMM systems using narrow band power line communications.

This device has been developed to reduce CPU computational load in PLC systems running PRIME protocols. ATPL210 includes all necessary resources to be used as main controller in metering applications, and allows an external device to communicate according to PLC PRIME specifications.



## 1. Block Diagram

Figure 1-1. ATPL210A 120-pin Block Diagram

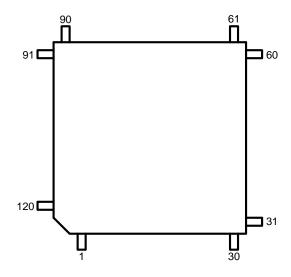




# 2. Package and Pinout

## 2.1 **120-Lead LQFP Package Outline**

Figure 2-1. Orientation of the 120-Lead Package





## 2.2 120-Lead LQFP Pinout

Table 2-1. ATPL210A 120-Lead LQFP pinout

1	
1	A17
2	A9
3	GND
4	VCC
5	/R_WE
6	D4
7	D3
8	D5
9	D2
10	D6
11	D1
12	D7
13	D0
14	VCC
15	GND
16	VDD
17	/R_OE
18	/R_CE
19	A8
20	A0
21	A7
22	A1
23	A6
24	A2
25	A5
26	GND
27	VCC
28	A3
29	A4
30	P4.5/MISO1

	-
31	P4.4/MOSI1
32	P4.3/SPICLK1
33	P4.2/SS1
34	P3.0/RxD0
35	P3.1/TxD0
36	VCC
37	GND
38	EMIT.1
39	EMIT.2
40	EMIT.3
41	EMIT.4
42	VCC
43	GND
44	EMIT.5
45	EMIT.6
46	EMIT.7
47	EMIT.8
48	VCC
49	GND
50	EMIT.9
51	EMIT.10
52	EMIT.11
53	EMIT.12
54	VCC
55	GND
56	AFE_HIMP
57	AFE_TXRX
58	VSENSE
59	PSENSE
60	VNR

61	TDI		
62	TMS		
63	TDO		
64	GND		
65	GND		
66	VCC		
67	TRST		
68	TCK		
69	RSTA		
70	D_INIT		
71	GND		
72	VCC		
73	GND		
74	VDD		
75	LDO_PD		
76	VSS0		
77	VDE0		
78	VDE0		
79	GND		
80	GND		
81	VCC		
82	CLKEA		
83	GND		
84	CLKEB		
85	VCC		
86	/EWDG		
87	DEBUG		
88	EXTRAM		
89	/PROG		
90	SECURED		

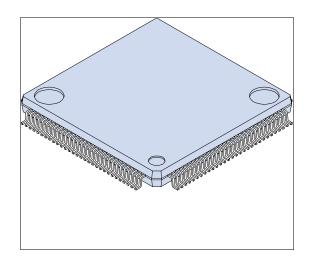
91	P5.4/RxD1
92	P5.5/TxD1
93	NC
94	P4.6/T2/AGC1
95	AGC0
96	GND
97	VCC
98	AVS2
99	AVD2
100	AVS1
101	AVD1
102	VRH
103	VIN
104	VRL
105	GND
106	VCC
107	P5.0/SS0
108	P5.3/MISO0
109	P5.2/MOSI0
110	P5.1/SPICLK0
111	P1.7/SSN
112	A13
113	A14
114	GND
115	VCC
116	A12
117	A15
118	A11
119	A16
120	A10



## 3. Mechanical Characteristics

Figure 3-1. 120-lead LQFP Package Mechanical Drawing

120-pin plastic LQFP



Lead pitch	0.40 mm	
Pa ckage width · package length	14.0 mm · 14.0 mm	
Lead shape	Gullwing	
Sealing method	Plastic mold	
Mounting height	1.70 mm MAX	
Code (Ref erence )	P-LFQFP120-14 · 14-0.4 0	

### 120-pin plastic LQFP

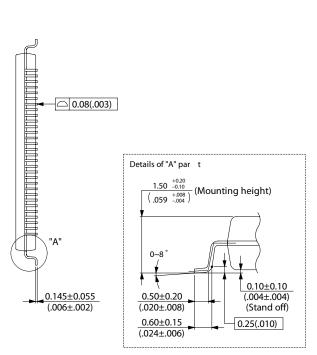
16.00±0.20(.630±.008)SQ

\*14.00±0.10(.551±.004)SQ

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- Note 1) \*: These dimensions do not include resin protrusion. Note 2) Pins width and pins thickness include plating thickness.
- Note 3) Pins width do not include tie bar cutting remainder.



Dimensions in mm (inches). Note: The values in parentheses are reference values.

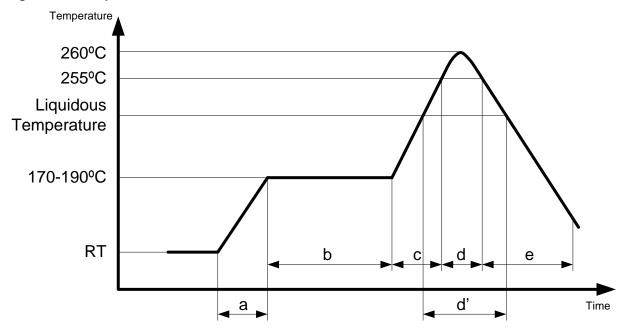
# 4. Recommended mounting conditions

### 4.1 Conditions of Standard Reflow

Table 4-1. Conditions of standard Reflow

Items	Contents	
Method	IR(Infrared Reflow)/Convection	
Times	2	
Floor Life	Before unpacking	Please use within 2 years after production
	From unpacking to second reflow	Within 8 days
	In case over period of floor life	Baking with 125°C +/- 3°C for 24hrs +2hrs/-0hrs is required. Then please use within 8 days. (please remember baking is up to 2 times)
Floor Life Condition	Between 5°C and 30°C and also below 70%RH required. (It is preferred lower humidity in the required temp range.)	

Figure 4-1. Temperature Profile



Note: H rank: 260°C Max

a: Average ramp-up rate: 1°C/s to 4°C/s

**b:** Preheat & Soak: 170°C to 190°C, 60s to 180s

c: Average ramp-up rate: 1°C/s to 4°C

d: Peak temperature: 260°C Max, up to 255°C within 10s

d': Liquidous temperature: Up to 230°C within 40s or

Up to 225°C within 60s or

Up to 220°C within 80s

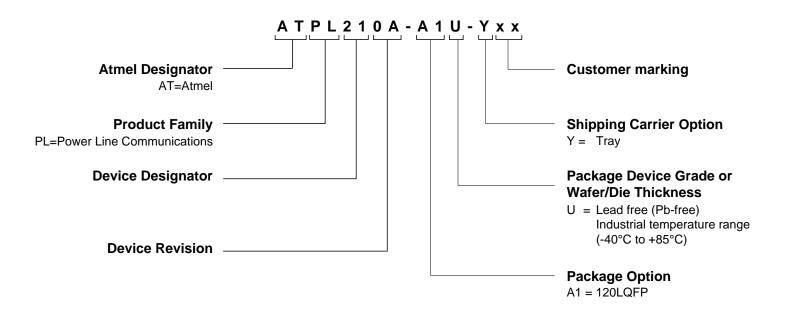
e: Cooling: Natural cooling or forced cooling



# 5. Ordering Information

Table 5-1. Atmel ATPL210A Ordering Codes

Atmel Ordering Code	Package	Package Type	Temperature Range
ATPL210A-A1U-Y	120 LQFP	Pb-Free	Industrial (-40°C to 85°)





# 6. Revision History

Doc. Rev.	Date	Comments
1.00	30/03/2012	Initial release





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#### **Atmel Corporation**

2325 Orchard Parkway San Jose, CA 95131

**Tel:** (+1)(408) 441-0311 **Fax:** (+1)(408) 487-2600

www.atmel.com

#### **Atmel Asia Limited**

Unit 01-5 & 16, 19F BEA Tower, Millennium City 5 418 Kwun Tong Road Kwun Tong, Kowloon HONG KONG

**Tel:** (+852) 2245-6100 **Fax:** (+852) 2722-1369

#### Atmel Munich GmbH

Business Campus
Parkring 4
D-85748 Garching b. Munich
GERMANY

**Tel:** (+49) 89-31970-0 **Fax:** (+49) 89-3194621

#### Atmel Japan G.K.

16F Shin-Osaki Kangyo Building 1-6-4 Osaki

Shinagawa-ku, Tokyo 141-0032

JAPAN

**Tel:** (+81)(3) 6417-0300 **Fax:** (+81)(3) 6417-0370

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